

JSR ELPAC™ AD series

Under development

Highly Adhesive, Highly Dispersive Materials

~Expected applications in next-generation electronics~



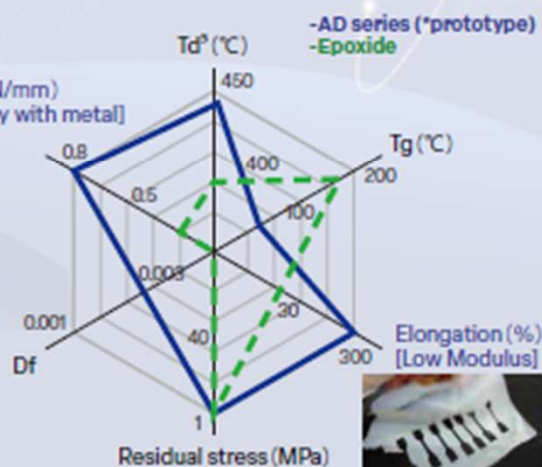
New Core unit

- Highly adhesion
- Highly dispersion

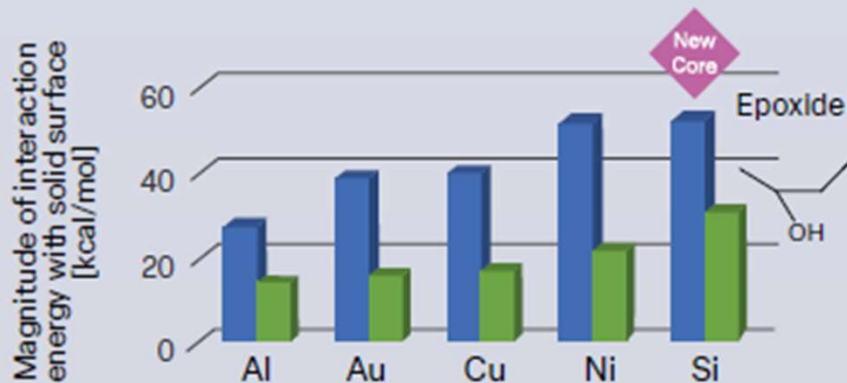
Application examples

- ✓ Substrate materials (CCL, Prepreg, Build UP)
- ✓ Molding compound
- ✓ High thermal conductive materials

Peel strength (Cu,N/mm)
[Good compatibility with metal]



Prediction of adhesion
by Quantum Espresso (computational science)



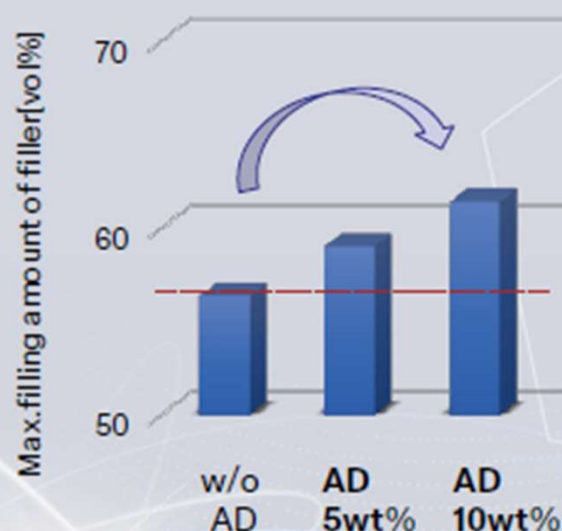
-New Core can interact various solid surface.

Dispersibility of filler with AD



-AD can suppress precipitation.

Examination of SiO₂ dispersion
in epoxy resin w or w/o AD



-High filling amount of filler can be possible by adding AD series.

Viscosity vs. addition amount of filler
in epoxy resin w or w/o AD

